



## Device Material Content

5555 NE Moore Ct.  
Hillsboro OR 97124  
[custreq@latticesemi.com](mailto:custreq@latticesemi.com)

Assembly: ASEM  
Size (mm): 17 x 17

**Package Code:**

**FTG256**

Lead pitch (mm): 1.0

MSL: 3

Reflow max (°C): 260

**Package: 256 ftBGA (option 3)**

**Total Device Weight 0.803 Grams**

**Products:**

XO2

October, 2020

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
<b>Die</b>	1.39%	0.0112	1.39%	0.0112	Silicon chip	7440-21-3	100.00%	Die size: 4.41 x 4.36 mm
<b>Mold Compound</b>	54.23%	0.4353	3.80%	0.0305	Epoxy Resin	-	7.00%	Mold Compound: Sumitomo G750SE (ULA)
			2.71%	0.0218	Phenol Novolac	9003-35-4	5.00%	
			2.71%	0.0218	Metal Hydroxide	-	5.00%	
			0.27%	0.0022	Carbon Black	1333-86-4	0.50%	
			44.74%	0.3591	Silica Fused	60676-86-0	82.50%	
<b>D/A Epoxy</b>	0.20%	0.0016	0.16%	0.00128	Silver	7440-22-4	80.00%	Die attach epoxy: Henkel (Ablebond) 2100A
			0.04%	0.00032	Esters & resins	-	20.00%	
<b>Wire</b>	0.19%	0.0015	0.19%	0.0015	Copper	7440-50-8	98.50%	0.8 mil diameter; 1 wire per solder ball
			0.00%	0.0000	Palladium	7440-05-3	1.50%	
<b>Solder Balls</b>	15.49%	0.1243	14.95%	0.1200	Tin (Sn)	7440-31-5	96.50%	SAC305
			0.46%	0.0037	Silver (Ag)	7440-22-4	3.00%	
			0.08%	0.0006	Copper (Cu)	7440-50-8	0.50%	
<b>Substrate</b>	13.02%	0.1045	8.85%	0.0711	Glass fiber	65997-17-3	68.00%	BT Resin CCL-HL832NX-A
			4.17%	0.0334	BT Resins	-	32.00%	
<b>Solder Mask</b>	5.97%	0.0479	3.36%	0.0269	Quartz	14808-60-7	56.20%	Solder mask PSR4000 AUS 308
			0.96%	0.0077	3-methoxy-3-methylbutylacetate	103429-90-9	16.00%	
			1.31%	0.0105	Barium Sulfate	7727-43-7	22.00%	
			0.18%	0.0014	Talc	14807-96-6	3.00%	
			0.03%	0.0002	Naphthalene	91-20-3	0.50%	
			0.14%	0.0011	Trade secret ingredients	-	2.30%	
<b>Foil</b>	9.50%	0.0762	8.09%	0.0649	Copper	7440-50-8	85.15%	
			1.36%	0.0109	Nickel plating	7440-02-0	14.28%	
			0.05%	0.0004	Gold plating	7440-57-5	0.57%	

Lattice regards this materials information to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Lattice subcontract the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Lattice has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Lattice products.

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Rev. Q



## Device Material Content

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**Package Code:**

**FTG256**

Assembly: ASEK

Size (mm): 17 x 17

Lead pitch (mm): 1.0

MSL: 3

Reflow max (°C): 260

**Package: 256 ftBGA (option 3)**

**Total Device Weight 0.803 Grams**

**Products:**

XO2

October, 2020

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
<b>Die</b>	1.39%	0.0112	1.39%	0.0112	Silicon chip	7440-21-3	100.00%	Die size: 4.41 x 4.36 mm
<b>Mold Compound</b>	54.23%	0.4353	47.45%	0.3809	Silica	60676-86-0	87.50%	Mold Compound: Kyocera KEG-2250LKDS (ULA)
			3.52%	0.0283	Epoxy resin	-	6.50%	
			2.98%	0.0239	Phenol Resin	-	5.50%	
			0.27%	0.0022	Carbon Black	1333-86-4	0.50%	
<b>D/A Epoxy</b>	0.20%	0.0016	0.16%	0.00128	Silver	7440-22-4	80.00%	Die attach epoxy: Henkel (Ablebond) 2100A
			0.04%	0.00032	Esters & resins	-	20.00%	
<b>Wire</b>	0.19%	0.0015	0.19%	0.0015	Copper	7440-50-8	98.50%	0.8 mil diameter; 1 wire per solder ball
			0.00%	0.0000	Palladium	7440-05-3	1.50%	
<b>Solder Balls</b>	15.49%	0.1243	15.26%	0.1225	Tin (Sn)	7440-31-5	98.50%	SAC105
			0.15%	0.0012	Silver (Ag)	7440-22-4	1.00%	
			0.08%	0.0006	Copper (Cu)	7440-50-8	0.50%	
<b>Substrate</b>	13.02%	0.1045	8.85%	0.0711	Glass fiber	65997-17-3	68.00%	BT Resin CCL-HL832NX-A
			4.17%	0.0334	BT Resins	-	32.00%	
<b>Solder Mask</b>	5.97%	0.0479	3.36%	0.0269	Quartz	14808-60-7	56.20%	Solder mask PSR4000 AUS 308
			0.96%	0.0077	3-methoxy-3-methylbutylacetate	103429-90-9	16.00%	
			1.31%	0.0105	Barium Sulfate	7727-43-7	22.00%	
			0.18%	0.0014	Talc	14807-96-6	3.00%	
			0.03%	0.0002	Naphthalene	91-20-3	0.50%	
			0.14%	0.0011	Trade secret ingredients	-	2.30%	
<b>Foil</b>	9.50%	0.0762	8.09%	0.0649	Copper	7440-50-8	85.15%	
			1.36%	0.0109	Nickel plating	7440-02-0	14.28%	
			0.05%	0.0004	Gold plating	7440-57-5	0.57%	

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October, 2020

**Package: 256 ftBGA (option 3)**  
**Total Device Weight 0.803 Grams**

**Package Code:**

**FTG256**

**Products:**

XO2

Assembly: ATP

Size (mm): 17 x 17

Lead pitch (mm): 1.0

MSL: 3

Reflow max (°C): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
<b>Die</b>	1.39%	0.0112	1.39%	0.0112	Silicon chip	7440-21-3	100.00%	Die size: 4.41 x 4.36 mm
<b>Mold Compound</b>	54.23%	0.4353	3.80%	0.0305	Epoxy Resin	-	7.00%	Mold Compound: Hitachi GE-110LS-V (ULA)
			2.71%	0.0218	Phenol Resin	-	5.00%	
			46.10%	0.3700	Silica Fused	60676-86-0	85.00%	
			1.36%	0.0109	Metal Hydroxide	-	2.50%	
			0.27%	0.0022	Carbon Black	1333-86-4	0.50%	
<b>D/A Epoxy</b>	0.20%	0.0016	0.16%	0.00128	Silver	7440-22-4	80.00%	Die attach epoxy: Henkel (Ablebond) 2300
			0.04%	0.00032	Esters & resins	-	20.00%	
<b>Wire</b>	0.19%	0.0015	0.19%	0.0015	Copper	7440-50-8	98.50%	0.8 mil diameter; 1 wire per solder ball
			0.00%	0.0000	Palladium	7440-05-3	1.50%	
<b>Solder Balls</b>	15.49%	0.1243	14.79%	0.1187	Tin (Sn)	7440-31-5	95.50%	SAC405
			0.62%	0.0050	Silver (Ag)	7440-22-4	4.00%	
			0.08%	0.0006	Copper (Cu)	7440-50-8	0.50%	
<b>Substrate</b>	13.02%	0.1045	8.85%	0.0711	Glass fiber	65997-17-3	68.00%	BT Resin CCL-HL832NX-A
			4.17%	0.0334	BT Resins	-	32.00%	
<b>Solder Mask</b>	5.97%	0.0479	3.36%	0.0269	Quartz	14808-60-7	56.20%	Solder mask PSR4000 AUS 308
			0.96%	0.0077	3-methoxy-3-methylbutylacetate	103429-90-9	16.00%	
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<b>Foil</b>	9.50%	0.0762	8.09%	0.0649	Copper	7440-50-8	85.15%	
			1.36%	0.0109	Nickel plating	7440-02-0	14.28%	
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